QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: CAAN-20ZQHX554

Date:
February 25, 2026

Qualification of ANAP as an additional assembly site for EMC2106-DZK-TR catalog part number (CPN) available in 28L VQFN (5x5x0.9mm) package.

MICROCHIP

PACKAGE QUALIFICATION REPORT

Purpose	Qualification of ANAP as an additional assembly site for EMC2106-DZK-TR catalog part number (CPN) available in 28L VQFN (5x5x0.9mm) package.
CN	E000276909
QUAL ID	R2500993 Rev. A
Bonding No.	BD - 003127 Rev.01
MP CODE	TG701TRLXBC0
Part No.	EMC2106-DZK-TR
CCB No.	7534

Lead Frame

Paddle size	130 x 130mils
Material	C194
Surface	Ag
Process	Etched
Lead lock	No
Part number	101348939
Plating composition	MatteSn

Bond Wire

Wire	CuPdAu

Die Attach Material

Epoxy	8290

Mold Compound

Mold compound	G700

Package

Type	28L VQFN
Package size	5 x 5 x 0.9mm

MICROCHIP

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
ANAP260800001.000	GF35925010772.B00	2521Y1V
ANAP260800002.000	GF35925010772.B00	2521Y1W
ANAP260800003.000	GF35925010772.B00	2521Y1Y

Result [X] Pass [ ] Fail [ ] _____

28L VQFN (5x5x0.9mm) assembled by ANAP pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 3 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
<u>Precondition Prior Perform Reliability Tests</u> (At MSL Level 3)	**Electrical Test:** +25°C and 50°C System: EX_DIGITAL	JESD22-A113	693(0)	0/693	Pass	Good Devices
	Bake 150°C, 24 hrs. System: CHINEE	JIP/ IPC/JEDEC J-STD-020E		693		
	30°C/60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test: +25°C and 50°C System: EX_DIGITAL		693(0)	0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	**Stress Condition:** -65°C to +150°C, 500 Cycles System: TABAI ESPEC TSA-70H	JESD22-A104		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +50°C System: EX_DIGITAL		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>3.00 grams)		15(0)	0/15	Pass	
UNBIASED-HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: EX_DIGITAL		231(0)	0/231	Pass	77 units / lot
HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. **Bias Volt:** 3.3 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C and 50°C System: EX_DIGITAL		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 504 hrs. System: TPS Bake Oven **Electrical Test:** +25°C and 50°C System: EX_DIGITAL	JESD22-A103	 135(0)	135 0/135	 Pass	45 units /lots
Solderability Temp 215°C	**Steam Aging:** Temp 93°C, 8Hrs System: SAS-3000 **Solder Dipping:** Solder Temp 215°C **Solder material:** SnPb Sn63, Pb37 System: ERSA RA 2200D **Visual Inspection:** External Visual Inspection	J-STD-002	 22(0)	22 22 0/22	 Pass	
Solderability Temp 245°C	**Steam Aging:** Temp 93°C, 8Hrs System: SAS-3000 **Solder Dipping:** Solder Temp.245°C **Solder material:** Pb Free Sn 95.5Ag3.9 Cu0.6 System: ERSA RA 2200D **Visual Inspection:** External Visual Inspection	J-STD-002	 22(0)	22 22 0/22	 Pass	
Wire sweep	Wire sweep Inspection 15 Wires / lot	-	45(0) Wires	0/45	Pass	
Physical Dimensions	Physical Dimension, 10 units / 1 lot	JESD22-B100/B108	30(0) Units	0/30	Pass	
Bond Strength Data Assembly	Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)	Mil. Std. 883-2011 CDF-AEC-Q100-001	30(0) Wires 30(0) Bonds	0/30 0/30	Pass Pass	